



**Features and Benefits** 

Low On-Resistance Low Input Capacitance Fast Switching Speed Low Input/Output Leakage

**Mechanical Data** 

Case: SOT23

## **Product Summary**

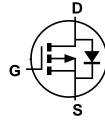
BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C
001/	$62m\Omega @ V_{GS} = -4.5V$	-3.8A
-20V	90mΩ @ V <sub>GS</sub> = -2.5V	-3.1A

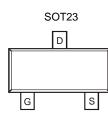
# **Description and Applications**

This MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>), yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- Battery Charging
- Power Management Functions
- DC-DC Converters
- Portable Power Adaptors







P-CHANNEL ENHANCEMENT MODE MOSFET

Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2) Halogen- and Antimony-Free. "Green" Device (Note 3)

Case Material: Molded Plastic, "Green" Molding Compound.

Terminals: Finish-Matte Tin Annealed over Copper Lead-Frame.

UL Flammability Classification Rating 94V-0 Moisture Sensitivity: Level 1 per J-STD-020

Solderable per MIL-STD-202, Method 208 @3

Terminals Connections: See Diagram Below

Weight: 0.009 grams (Approximate)

Top View

Internal Schematic

Top View

### Ordering Information (Note 4)

Part Number	Case	Packaging
DMP2120U-7	SOT23	3,000/Tape & Reel
DMP2120U-13	SOT23	10,000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# **Marking Information**

	SOT	23
	212	ΥM
-		

212 = Product Type Marking Code
YM = Date Code Marking
Y or $\overline{Y}$ = Year (ex: H = 2020)
M or $\overline{M}$ = Month (ex: 9 = September)

Date Code Key

20.0 0000												
Year	2017	~		2020	20	021	2022	2	2023	2024		2025
Code	E	~		Н			J		K	L		М
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



## Maximum Ratings (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Drain-Source Voltage	V <sub>DSS</sub>	-20	V		
Gate-Source Voltage	V <sub>GSS</sub>	±8	V		
		T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	-3.8 -3.0	A
Maximum Continuous Body Diode Forward Curr	ent (Note 6	6)	Is	-1.3	A
Pulsed Drain Current (10µs Pulse, Duty Cycle =	1%)	IDM	-20	A	

## **Thermal Characteristics**

Characteristic		Symbol	Value	Unit	
Total Power Dissipation (Note 5)		PD	0.8	W	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	5	163	°C/W	
mermai Resistance, Junction to Ambient (Note 5)	t<10s	$R_{ extsf{ heta}JA}$	114	C/VV	
Total Power Dissipation (Note 6)		PD	1.3	W	
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	Devi	94	°C/W	
mermai Resistance, Junction to Ambient (Note 6)	t<10s	R <sub>θJA</sub>	66	0/22	
Operating and Storage Temperature Range		T <sub>J,</sub> T <sub>STG</sub>	-55 to +150	°C	

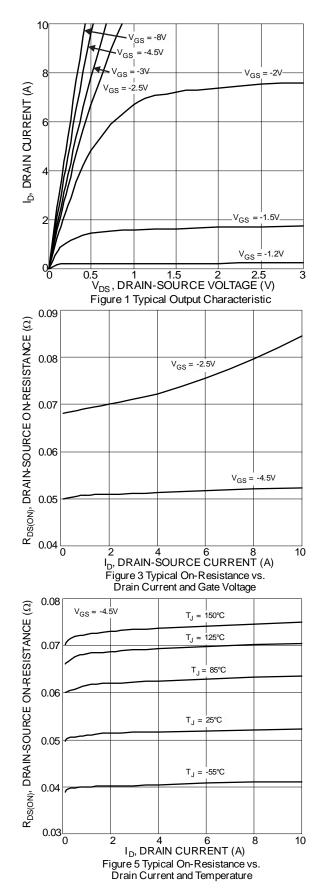
# Electrical Characteristics (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

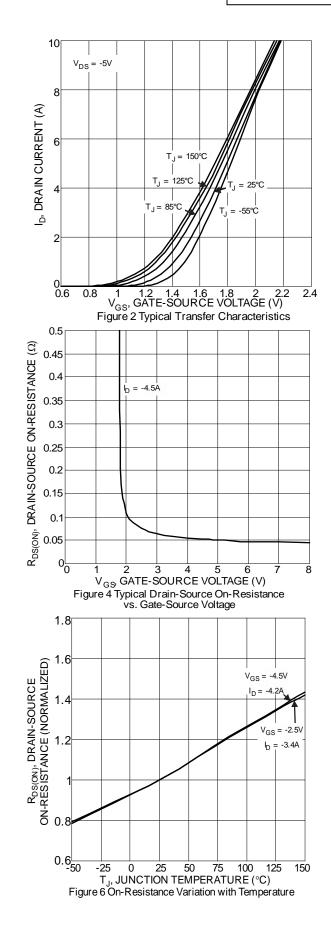
		-				-	
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-20			V	$V_{GS} = 0V, I_D = -250 \mu A$	
Zero Gate Voltage Drain Current $T_J = +25^{\circ}C$	IDSS	_	—	-1.0	μA	$V_{DS} = -20V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	—	—	±100	nA	$V_{GS} = \pm 8V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-0.4	_	-1.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
			51	62		Vgs = -4.5V, ID = -4.2A	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	—	71	90	mΩ	Vgs = -2.5V, ID = -3.4A	
	. ,		116	150		Vgs = -1.8V, ID = -2.0A	
Diode Forward Voltage	V <sub>SD</sub>	—	-0.7	-1.1	V	$V_{GS} = 0V, I_{S} = -1A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss		487	—	pF		
Output Capacitance	Coss		60	—	pF	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V, f = 1.0MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>	_	53	—	pF	1 = 1:000112	
Gate Resistance	R <sub>G</sub>		39	—	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	
Total Gate Charge	Q <sub>G</sub>		6.3	—	nC		
Gate-Source Charge	Q <sub>GS</sub>	_	0.7	—	nC	V <sub>GS</sub> = -4.5V, V <sub>DS</sub> = -4V, -I <sub>D</sub> = -3.5A	
Gate-Drain Charge	Q <sub>GD</sub>		1.4	—	nC	ID = -3.5 R	
Turn-On Delay Time	t <sub>D(ON)</sub>	_	5.3		ns		
Turn-On Rise Time	t <sub>R</sub>		15.7	—	ns	$V_{DS} = -4V, V_{GS} = -4.5V,$	
Turn-Off Delay Time	t <sub>D(OFF)</sub>		38.5	_	ns	$I_D = -1.0A, R_G = 6\Omega$	
Turn-Off Fall Time	t <sub>F</sub>		23.2		ns		
Body Diode Reverse Recovery Time	t <sub>RR</sub>	_	7.5	—	ns	I <sub>S</sub> = -2.0A, di/dt = -100A/µs	
Body Diode Reverse Recovery Charge	Q <sub>RR</sub>	_	1.9	_	nC	I <sub>S</sub> = -2.0A, di/dt = -100A/µs	

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

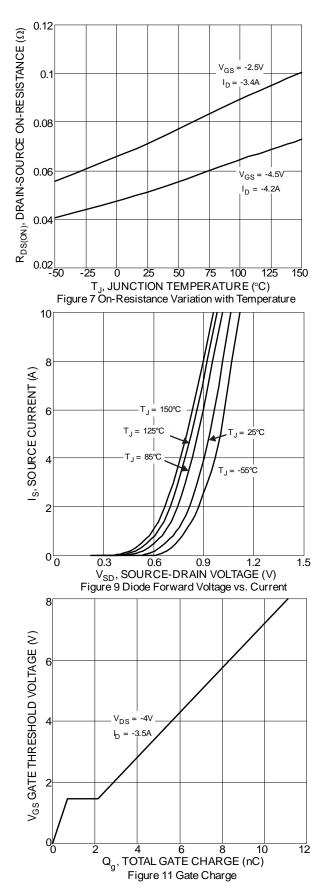
Device mounted on FR-4 substrate PC board, 202 copper, with 1inch square copper plate.
Short duration pulse test used to minimize self-heating effect.
Guaranteed by design. Not subject to product testing.

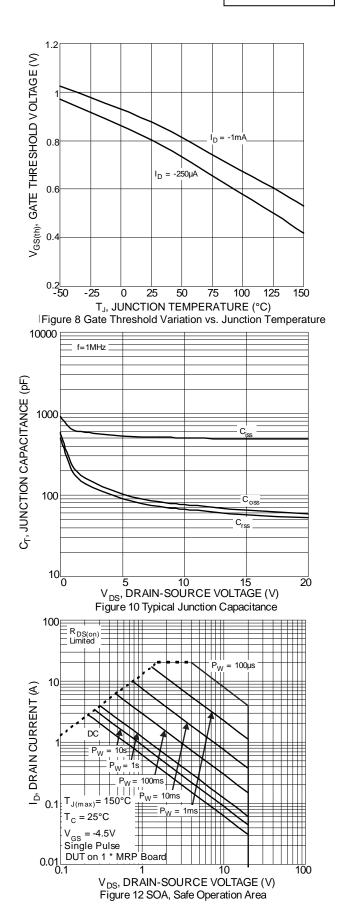




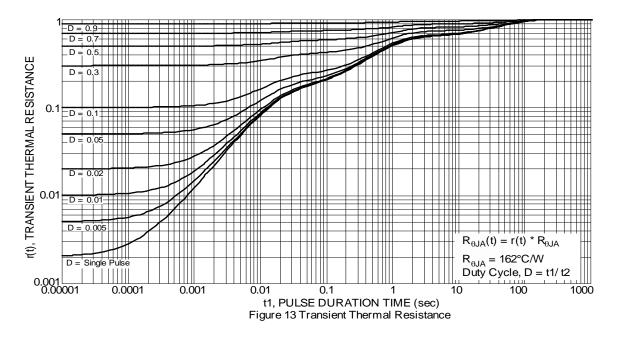








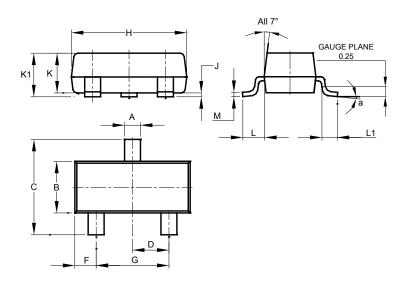






## **Package Outline Dimensions**

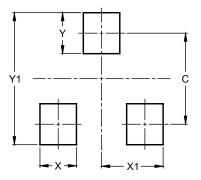
Please see http://www.diodes.com/package-outlines.html for the latest version.



	SOT23								
Dim	Min	Max	Тур						
Α	0.37	0.51	0.40						
В	1.20	1.40	1.30						
С	2.30	2.50	2.40						
D	0.89	1.03	0.915						
F	0.45	0.60	0.535						
G	1.78	2.05	1.83						
Н	2.80	3.00	2.90						
J	0.013	0.10	0.05						
K	0.890	1.00	0.975						
K1	0.903	1.10	1.025						
L	0.45	0.61	0.55						
L1	0.25	0.55	0.40						
М	0.085	0.150	0.110						
а	0°	8°							
All	Dimens	ions in	mm						

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	2.0
Х	0.8
X1	1.35
Y	0.9
Y1	2.9



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